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Serial No.: 10/651,813 Examiner: Williams, Alexander O.  
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Title: SEMICONDUCTOR CHIP HAVING BOND PADS AND MULTI-CHIP PACKAGE

INFORMATION DISCLOSURE CITATION  
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U.S. PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Issue Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub Class</u>
<u>QV</u>	—	4,723,197	Feb. 2, 88	Takiar et al.		
<u>BA</u>	—	5,502,289	Mar. 26, 96	Takiar et al		
<u>PA</u>	—	5,834,844	Nov. 10, 98	Akagawa et al		
<u>PA</u>	—	6,175,149	Jan. 16, 01	Akram		
<u>PA</u>	—	6,498,396 B1	Dec. 24, 02	Arino		

FOREIGN PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country</u>	<u>Name</u>
<u>BA</u>	—	DE 19610302 A1	Oct. 2, 96	Germany, (Corresponds to US 6,498,396 B1)	
<u>BA</u>	—	EP 1094517 A2	Apr. 25, 01	Europe	
<u>BA</u>	—	EP 0221496 A2	May 13, 87	Europe	
<u>BA</u>	—	2000058743 A	Feb. 25, 00	Japan	

OTHER DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
<u>PA</u>	—	Yasunaga, et al. "Chip Scale Package: "A Light Dressed LSI Chip" IEEE transactions on component, packaging and Manufacturing technology part A. Vol. 18, No. 3. September 1995, pp. 451-457

Examiner:

Date Considered:

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